





#### **Features**

- 3.5mm X 3.5mm X 1.15mm SMD LED
- Zener diode provided for ESD Protection
- IR-reflow compatible
- Ideal for accent lighting
- Standard Package: 2,000pcs / Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant





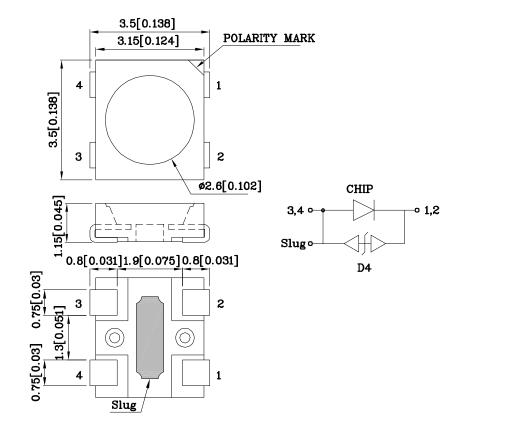


# ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

#### Applications

- Signal and symbol luminaire for orientation.
- Marker lights (e.g. steps, exit ways, etc).
- Decorative and entertainment lighting.
- Commercial and residential lighting.
- Automotive interior lighting.

#### **Package Schematics**



#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25 (0.01")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.



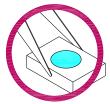
3.5x3.5 mm SMD CHIP LED LAMP

#### **Handling Precautions**

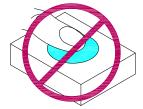
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

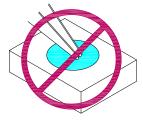
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

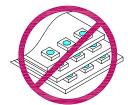


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

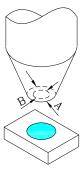




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Dec 16, 2013



3.5x3.5 mm SMD CHIP LED LAMP

#### **Selection Guide**

Part Number	Emitting Color	Emitting Material	$\begin{array}{c} \text{CIE12} \\ \text{Lens-color} \end{array}$		$\begin{array}{c} Luminous \ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}150\text{mA}) \\ cd \end{array}$		ous Flux 7-2007* 50mA) m	Viewing Angle 2 θ 1/2 [1]
				min.	typ.	min.	typ.	
XZMD20X92S-4	Deep-Red	AlGaInP	Water Clear	1.6*	2.09*	5*	6.3*	120°

#### Notes:

- 1.  $\theta$  1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity / luminous flux: +/-15%.
- 3. LEDs are binned according to their luminous flux.

#### Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	PD	465	mW	
Junction Temperature [1]	TJ	120	°C	
Operating Temperature	Тор	-40 To +100	°C	
Storage Temperature	Tstg	-40 To +110	°C	
DC Forward Current [1]	IF	150	mA	
Reverse Voltage	VR	5	V	
Peak Forward Current [2]	IFM	270	mA	
Thermal Resistance [1] (Junction/ambient)	Rth j-a	178	°C/W	
Thermal Resistance [1] (Junction/solder point)	Rth j-S	78	°C/W	
Electrostatic Discharge Threshold (HBM)	8000	V		

#### Notes:

#### Electrical / Optical Characteristics at Ta=25°C

Damanaskan	G 1.1	Valı	TT '4		
Parameter	Symbol	Typ.	Max.	Unit	
Wavelength at peak emission CIE127-2007* IF=150mA	λpeak	660*		nm	
Dominant Wavelength CIE127-2007* IF=150mA	λdom [1]	640*		nm	
Spectral bandwidth at 50% $\Phi$ Rel Max $$ If = 150mA	$\triangle \lambda$	20		nm	
Forward Voltage IF=150mA	VF [2]	2.5	3.1	V	
Allowable Reverse Current	IR		85	mA	
Temperature coefficient of $\lambda$ peak IF=150mA, -10°C $\leq$ T $\leq$ 100°C	ТСАреак	0.09		nm/°C	
Temperature coefficient of $\lambda$ dom IF=150mA, -10°C $\leq$ T $\leq$ 100°C	TCλdom	0.03		nm/°C	
Temperature coefficient of $VF$ $IF=150mA$ , $-10$ °C $\leq T\leq 100$ °C	TCv	-2.7		mV/°C	

#### Notes:

 $<sup>^{\</sup>star}$  Luminous intensity / luminous flux value is in accordance with CIE127-2007 standards.

<sup>1.</sup> Rth(j-a) Results from mounting on PC board FR4 (pad size  $\!\!\!\! \geq \!\! 16$  mm² per pad)

<sup>2. 1/10</sup> Duty Cycle, 0.1ms Pulse Width.

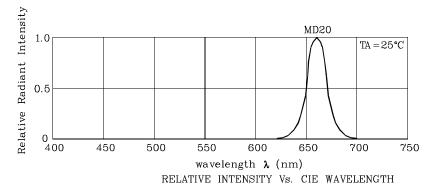
<sup>1.</sup> The dominant Wavelength ( $\lambda d$ ) above is the setup value of the sorting machine. (Tolerance  $\lambda d$ :  $\pm 1 nm$ .)

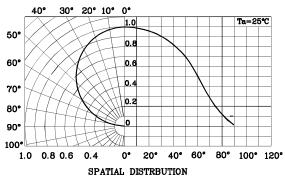
<sup>2.</sup> Forward Voltage: +/-0.1V.

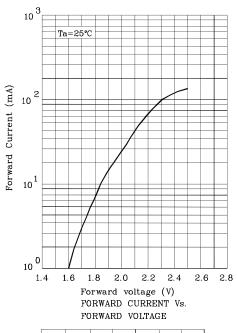
<sup>\*</sup>Wavelength value is in accordance with CIE127-2007 standards.

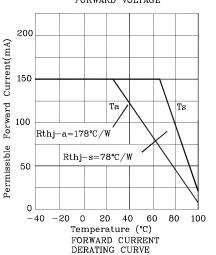


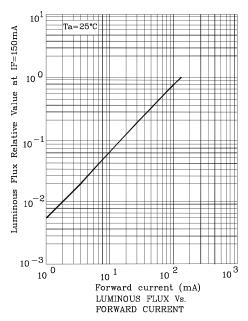


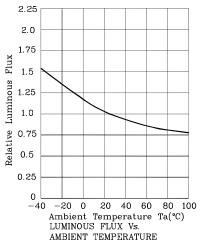






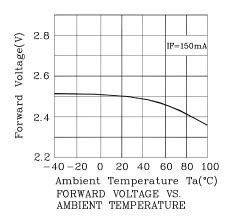


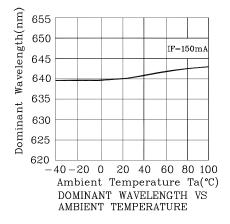


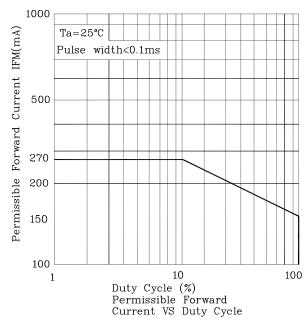










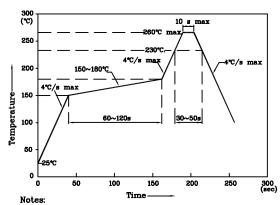




# SunLED www.SunLEDusa.com

### **❖** LED is recommended for reflow soldering and soldering profile is shown below.

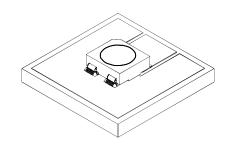
Reflow Soldering Profile for SMD Products (Pb-Free Components)



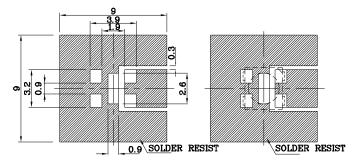
- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

## The device must be mounted according to the specifications.

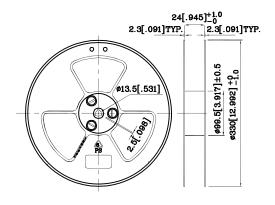
**❖** The device has a single mounting surface.



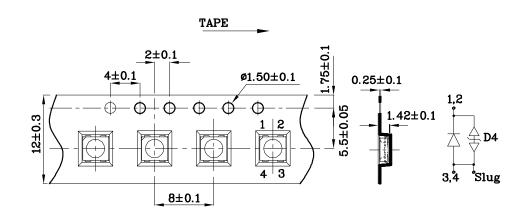
#### Recommended Soldering Pattern



#### Reel Dimension



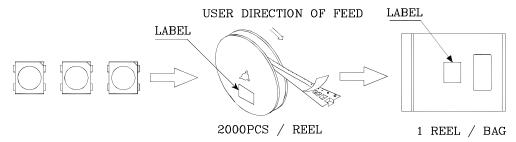
**❖** Tape Specification (Units:mm)

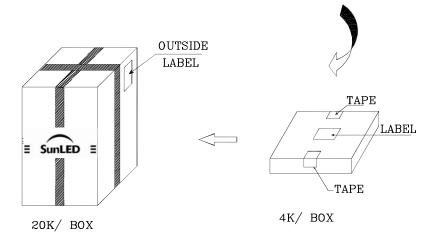


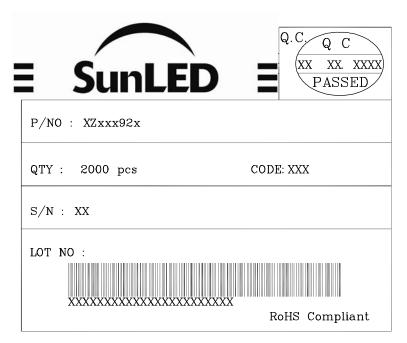




#### PACKING & LABEL SPECIFICATIONS







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- $2. \ Contents \ within \ this \ document \ are \ subject \ to \ improvement \ and \ enhancement \ changes \ without \ notice.$
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

Dec 16, 2013